

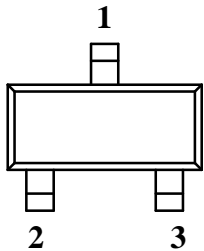
Silicon NPN Planar RF Transistor

Applications

Low noise, low current, low voltage, high gain, 50 Ohm transistor for 945 MHz cordless telephone, pager, and low current UHF remote control applications.

Features

- Low supply voltage
- Low current consumption
- 50 Ω input impedance at 945 MHz
- Low noise figure
- High power gain



94 9280

Marking: 852

Plastic case (SOT 23)

1 = Collector; 2 = Base; 3 = Emitter

Absolute Maximum Ratings

Parameters	Symbol	Value	Unit
Collector-base voltage	V_{CBO}	12	V
Collector-emitter voltage	V_{CEO}	6	V
Emitter-base voltage	V_{EBO}	2	V
Collector current	I_C	8	mA
Total power dissipation $T_{amb} \leq 125^\circ\text{C}$	P_{tot}	30	mW
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature range	T_{stg}	-65 to +150	$^\circ\text{C}$

Maximum Thermal Resistance

Parameters	Symbol	Maximum	Unit
Junction ambient on glass fibre printed board (25 x 20 x 1.5) mm ³ plated with 35 μm Cu	R_{thJA}	450	K/W

Electrical DC Characteristics

 $T_{amb} = 25^{\circ}\text{C}$

Parameters / Test Conditions	Symbol	Min.	Typ.	Max.	Unit
Collector-emitter cut-off current $V_{CE} = 12\text{ V}, V_{BE} = 0$	I_{CES}			100	μA
Collector-base cut-off current $V_{CB} = 8\text{ V}, I_E = 0$	I_{CBO}			100	nA
Emitter-base cut-off current $V_{EB} = 1\text{ V}, I_C = 0$	I_{EBO}			1	μA
Collector-emitter breakdown voltage $I_C = 1\text{ mA}, I_B = 0$	$V_{(BR)CEO}$	6			V
Collector-emitter saturation voltage $I_C = 5\text{ mA}, I_B = 0.5\text{ mA}$	V_{CEsat}		0.1	0.4	V
DC forward current transfer ratio $V_{CE} = 3\text{ V}, I_C = 1\text{ mA}$	h_{FE}	40	90		

Electrical AC Characteristics

 $T_{amb} = 25^{\circ}\text{C}$

Parameters / Test Conditions	Symbol	Min.	Typ.	Max.	Unit
Gain bandwidth product $V_{CE} = 3\text{ V}, I_C = 1\text{ mA}, f = 500\text{ MHz}$ $V_{CE} = 2\text{ V}, I_C = 1.5\text{ mA}, f = 500\text{ MHz}$	f_T f_T		4.7 5.2		GHz GHz
Collector-base capacitance $V_{CB} = 1\text{ V}, f = 1\text{ MHz}$	C_{cb}		0.2		pF
Noise figure $Z_S = Z_{Sopt}, f = 945\text{ MHz},$ $V_{CE} = 3\text{ V}, I_C = 1\text{ mA}$ $V_{CE} = 2\text{ V}, I_C = 1.5\text{ mA}$ $Z_S = Z_{Sopt}, f = 450\text{ MHz}$ $V_{CE} = 2\text{ V}, I_C = 0.5\text{ mA}$	F_{opt} F_{opt} F_{opt}		1.8 2.0 1.1		dB dB dB
Power gain $V_{CE} = 3\text{ V}, I_C = 1\text{ mA}, f = 945\text{ MHz}$ $V_{CE} = 2\text{ V}, I_C = 1.5\text{ mA}, f = 945\text{ MHz}$ $V_{CE} = 2\text{ V}, I_C = 0.5\text{ mA}, f = 450\text{ MHz}$	G_{pe} at F_{opt} G_{pe} at F_{opt} G_{pe} at F_{opt}		10.5 12.0 11.5		dB dB dB
Collector current for f_T max $V_{CE} = 2\text{ V}, f = 500\text{ MHz}$	I_C		3		mA
Real part of input impedance $V_{CE} = 3\text{ V}, f = 945\text{ MHz}, I_C = 1\text{ mA}$ $V_{CE} = 2\text{ V}, f = 945\text{ MHz}, I_C = 1.5\text{ mA}$	$Re_{(h11e)}$ $Re_{(h11e)}$		50 50		Ω Ω

 $f_S = \text{disturbance signal}, f_N = \text{useful signal}$

Common Emitter S-Parameter

$V_{CE} = 2 \text{ V}$, $I_C = 1.5 \text{ mA}$

f/MHz	S ₁₁		S ₂₁		S ₁₂		S ₂₂	
	LOG MAG	ANG	LOG MAG	ANG	LOG MAG	ANG	LOG MAG	ANG
	dB	deg	dB	deg	dB	deg	dB	deg
100	-0.66	-7.5	13.69	170.9	-35.83	84.8	-0.09	-3.9
200	-0.93	-14.5	13.43	161.7	-30.11	79.8	-0.25	-7.4
300	-1.33	-21.0	13.05	153.1	-26.98	75.1	-0.50	-10.6
400	-1.82	-27.0	12.61	145.1	-24.95	71.5	-0.79	-13.1
500	-2.36	-32.2	12.06	137.8	-23.48	68.3	-1.11	-15.3
600	-2.98	-36.8	11.52	131.3	-22.29	65.9	-1.42	-16.8
700	-3.58	-40.3	11.00	125.3	-21.39	63.6	-1.72	-17.8
800	-4.20	-43.8	10.45	120.0	-20.67	62.1	-1.98	-18.7
900	-4.79	-46.9	9.96	115.1	-20.05	61.2	-2.21	-19.5
1000	-5.36	-50.0	9.49	110.7	-19.46	60.3	-2.43	-20.3
1100	-5.99	-52.4	9.01	106.5	-18.97	59.5	-2.62	-20.8
1200	-6.56	-54.8	8.60	102.8	-18.56	59.3	-2.81	-21.4
1300	-7.15	-57.6	8.18	99.0	-18.20	58.7	-2.97	-21.7

Common Emitter S-Parameter

$V_{CE} = 2 \text{ V}$, $I_C = 0.5 \text{ mA}$

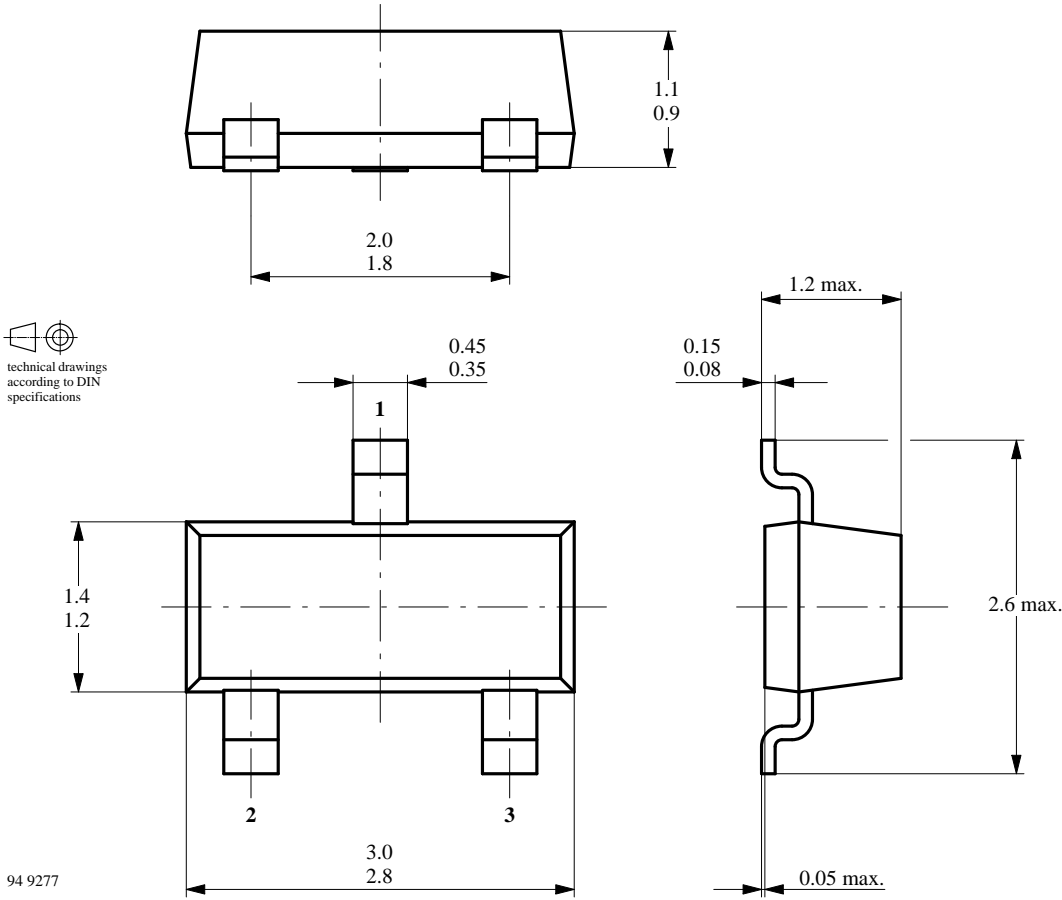
f/MHz	S ₁₁		S ₂₁		S ₁₂		S ₂₂	
	LOG MAG	ANG	LOG MAG	ANG	LOG MAG	ANG	LOG MAG	ANG
	dB	deg	dB	deg	dB	deg	dB	deg
100	-0.21	-3.8	4.67	174.9	-36.55	86.8	-0.02	-2.3
200	-0.27	-7.9	4.65	168.9	-30.62	83.4	-0.06	-4.7
300	-0.40	-11.7	4.63	163.3	-27.12	80.0	-0.14	-6.7
400	-0.55	-15.5	4.53	157.7	-24.72	76.8	-0.23	-8.7
500	-0.72	-18.9	4.31	151.9	-23.16	73.6	-0.36	-10.6
600	-0.91	-22.4	4.17	147.2	-21.68	71.5	-0.46	-12.4
700	-1.10	-25.8	3.98	142.2	-20.63	69.0	-0.58	-13.9
800	-1.30	-28.9	3.85	137.6	-19.68	66.7	-0.71	-15.5
900	-1.54	-32.3	3.72	133.1	-18.90	65.0	-0.83	-17.2
1000	-1.75	-35.4	3.52	129.4	-18.34	63.5	-0.93	-18.6
1100	-2.02	-38.8	3.44	125.1	-17.70	61.8	-1.07	-19.7
1200	-2.25	-41.5	3.29	121.3	-17.18	60.4	-1.18	-21.3
1300	-2.55	-45.1	3.18	117.2	-16.61	58.6	-1.32	-22.6

S 852 T

TEMIC

TELEFUNKEN Semiconductors

Dimensions of in mm



Ozone Depleting Substances Policy Statement

It is the policy of **TEMIC TELEFUNKEN microelectronic GmbH** to

1. Meet all present and future national and international statutory requirements.
2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

TEMIC TELEFUNKEN microelectronic GmbH semiconductor division has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively
2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA
3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

TEMIC can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

We reserve the right to make changes to improve technical design without further notice.

Parameters can vary in different applications. All operating parameters must be validated for each customer application by the customer. Should the buyer use TEMIC products for any unintended or unauthorized application, the buyer shall indemnify TEMIC against all claims, costs, damages, and expenses, arising out of, directly or indirectly, any claim of personal damage, injury or death associated with such unintended or unauthorized use.

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